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IC TAG STRUCTURE

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Abstract of **JP2000194820**

PROBLEM TO BE SOLVED: To provide an easy-to-destroy structure in the case of peeling off an IC tag. **SOLUTION:** In this IC tag structure for which the IC tag composed by providing a coil-like copper wire 4 to be an antenna and an IC chip, loading the IC chip on a substrate, constituting an IC module part 3 by connecting it to the pattern part of the substrate and connecting the pattern part of the substrate and the connection end part of the coil-like copper wire 4 is clamped by two films and adhered, in the case of peeling off the films, the coil-like copper wire 4 is peeled off in a state of being laminated to one of the films, the IC module part 3 is peeled off in a state of being laminated to the other film and they are respectively separated.

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